New Trends in Electrical Engineering Automatic Control, Computing and Communication Sciences

Edited by

Carlos A. Coello Coello Alexander Poznyak José Antonio Moreno Cadenas Vadim Azhmyakov

LOGOS Verlag, Berlin, Germany

Editors:

Dr. Carlos A. Coello Coello

CINVESTAV-IPN Departamento de Computación Av. IPN No. 2508 Mexico, D.F. 07360 Mexico. e-mail: ccoellocs.cinvestav.mx

Dr. Alexander Poznyak and Dr. Vadim Azhmyakov

CINVESTAV-IPN Departamento de Control Automático Av. IPN No. 2508 Mexico, D.F. 07360 Mexico. e-mail: apoznyak (vazhmyakov)@ctrl.cinvestav.mx

Dr. José Antonio Moreno Cadenas

CINVESTAV-IPN Departamento de Ingeniería Eléctrica Av. IPN No. 2508 Mexico, D.F. 07360 Mexico. e-mail: jmoreno@cinvestav.mx

To Lupita, Carlos Felipe and Víctor Eugenio Carlos A. Coello Coello To Polina and Ivan Alexander Poznyak To Elisa, Ely and Chris José Antonio Moreno Cadenas To Zuleima and Darien Vadim Azhmyakov

Preface

This book contains extended versions of selected papers presented at the 2008 5th International Conference on Electrical Engineering, Computing Science and Automatic Control (CCE'2008), which took place in Mexico City, México during 12–14 November, 2008.

This volume contains 28 chapters organized in four parts, each of them corresponding to one of the major topics covered in CCE'2008. Next, we provide a short description of each of these 28 chapters.

Part I contains the following 10 chapters related to automatic control and mechatronics:

In chapter 1, Lu investigates mixed finite element methods for semilinear optimal control problems. The author derives *a priori* error estimates for the coupled state and control approximation, and presents a numerical example that confirms the author's theoretical results.

Robles-Aguirre et al. present in chapter 2, the design of first and second order sliding mode controllers for the synchronous generator speed, Unified Power Flow Controller (UPFC) series power flows, UPFC voltage magnitude and UPFC internal DC link voltage. The authors use combinations of sliding mode and block control techniques to design these controllers, which are implemented in a small power system. Digital simulations are adopted by the authors to illustrate the effectiveness of the proposed approach.

Chapter 3, by Garrido and Miranda, presents a method for DC servomotors working in a closed loop. They use a proportional integral controller to stabilize the servomotor, and another one to close the loop around a linear model of the servomotor. A laboratory prototype is used to validate the proposed method.

VIII Preface

In chapter 4, Villafuerte and Mondié propose a new approach for the analysis of the case of neutral and retarded type time delay systems. Some examples and a case study are adopted to illustrate the proposed approach.

Galvan-Guerra and Azhmyakov consider, in chapter 5, the linear quadratic impulsive hybrid optimal control problem and apply to it the corresponding Pontryagintype maximum principle. The aim of the authors was to investigate the relationship between such a maximum principle and the Bellman dynamic programming approach. They also formulate the necessary optimality conditions for the problem of their interest and derive the associated Riccati-type equation, which allows an implementable numerical algorithm.

Chapter 6, by Garrido et al., presents a task-space controller for robot manipulators, which uses two proportional actions at joint and task levels. Such a topology exploits the fact that, in general, measurements at the task level are noisier than the measurements at the joint level. A planar 2-link revolute joint robot under visual feedback is used by the author to assess the performance of the proposed approach.

Sánchez and Collado propose in chapter 7, a modified version of the standard truncated Carleman linearization, which reduces the error in the truncation process. This modified approach is applied to two Van der Pol oscillators with slightly different frequencies.

Arias-Montiel and Silva-Navarro present in chapter 8 a LQR control scheme for unbalance compensation using an active magnetic bearing in a rotor-bearing system. Simulation and experimental results are included in the chapter to show the transient and steady-state behavior of the proposed closed-loop system.

In chapter 9, Cabrera-Amado and Silva-Navarro address the problem of unbalance compensation in a rotor-bearing system. The authors apply a semiactive balancing control scheme based on two radial MR dampers mounted in one of the supports. Some numerical simulations and experimental results on a physical platform are presented to validate the dynamic and robust performance of the proposed control system.

Finally, in chapter 10, Silva-Navarro et al. present the design of a passive/active autoparametric pendulum-type absorber to control the resonant vibrations in damped Duffing systems. Some simulation results are included in the chapter in order to illustrate the dynamic performance of the proposed system.

Part II contains 3 chapters related to solid-state materials and electron devices:

Chapter 11, by Juárez-Díaz et al., studies the effect of postgrowth thermal annealing processes on the optical characteristics of the zinc oxide (ZnO) films grown on (001) silicon substrates by DC reactive magnetron sputtering. The main motivation for this work was to enhance the PL response and to identify the origin of deep-level luminescence bands. Results indicate that the ZnO films annealing have potential applications in optoelectronic devices.

Albarrán et al. present in chapter 12 a description of the spinodal decomposition of the $GaSb_xN_yAs_{1-x-y}$ quaternary alloys lattice-matched to the GaAs as the result of the internal deformation and coherency strain energies. The authors show ranges of spinodal decomposition of the $GaSb_xN_yAs_{1-x-y}$ alloys up to $y \le 0.035$ with and without coherency strain energy.

Finally, in chapter 13, Morales-Sánchez et al. investigate the properties of amorphous and fcc polycrystalline $Ge_2Sb_2Te_5$ phases as well as the crystallization kinetics. The authors indicate that the various resistance states reached by annealing at different temperatures, suggest the possibility of using the $Ge_2Sb_2Te_5$ material as the active layer in a multi-state memory device.

Part III contains the following 7 chapters related to biomedical engineering, circuits and communication systems:

Vera et al., present in chapter 14, a study that compares four time-delay estimation methods, which relate temperature changes inside tissue replica (phantom) with time shifts in ultrasound echo-signals. The simulated signals were obtained from a numerical phantom which is proposed by the authors, and experimental signals were acquired from a specially developed agar phantom with uniformly distributed scatterers.

Chapter 15, by Ramírez-Mireles and Almada, presents a method for assessing the statistical nature of the multiple-access interference in wireless sensor networks. The authors propose a low-complexity method to establish "Gaussianity regions" in a two dimensional plane and determine the boundary of such regions for three different conditions: an ideal propagation channel with perfect and imperfect power control, as well as a multipath channel with "perfect average" power control.

In chapter 16, Cortez et al. present a family of hybrid codes, known as *LD STBC-VBLAST* codes, along with a receiver architecture suitable for low-complexity hardware implementation. The authors also present a correlated MIMO channel model and explore the impact of correlation on code performance. They show that *LD STBC-VBLAST* codes exhibit higher performance than other (recently-proposed) hybrid codes.

Lozano et al. present in chapter 17 a numerical integration considering shadowed and illuminated currents in physical optics in order to calculate the radiation pattern of antennas on complex structures modeled by NURBS. This approach is adopted for the case in which the antenna is placed at a distance less than one wavelength of the structure. The results are compared to measurements obtained with other physi-

X Preface

cal optics techniques, such as the stationary phase method or numerical integration considering only illuminated currents.

Medina-Vázquez et al. show in chapter 18, the differences and advantages that the multi-input floating gate MOS (MIFGMOS) transistor has versus the conventional CMOS transistor. In order to illustrate such differences, the authors design and implement both a voltage to current converter cell and a memory current cell using MIFGMOS transistors. The development is based in mathematical and simulation analysis as well as in experimental results.

In chapter 19, Aguirre-Hernandez and Linares-Aranda present an 8×8 -bits CMOS pipelined multiplier built using a full-adder cell with a new internal logic structure and a pass-transistor logic style that allow to get reduced delay and power consumption. A test chip containing the multiplier was fabricated using a $0.35\mu m$ CMOS technology. The authors could confirm, through experimental measurements, its operation at 1.2GHz with a power consumption of 180mW, for a supply voltage of 3.3V.

Finally, chapter 20, by Medina Hernández et al., presents a new model for the production of autowaves which is used for navigation control of a mobile robot. Necessary analytic conditions based on linear theory are established in such a way that a reaction-diffusion system has an oscillating behavior in the initial phase.

Part IV contains the following 8 chapters related to computer science and computer engineering:

Chapter 21, by Cazarez-Castro et al., introduces a type-2 fuzzy logic controller whose intended task is to achieve the output regulation of a servomechanism with backlash. The design of this controller is optimized by a genetic algorithm aiming to obtain the closed-loop system in which the load of the driver is regulated to a desired position.

In chapter 22, Ferretti et al. presents what aims to be a general approach to combine autonomous robot navigation with high-level reasoning. In their proposal, they integrate vision-based motion planning with defeasible decision making (using logic programming) for differential-wheeled robots.

Galán Hernández and León Chávez present, in chapter 23, an object-oriented model of an open source software e-learning platform called Moodle. The model was developed using the Unified Model Language, and includes an analysis of its security services and vulnerabilities.

In chapter 24, Algredo-Badillo et al., provide a study in which they show how the software radio paradigm can be used to implement in hardware several standard security architectures within a single flexible platform.

Preface XI

Chapter 25, by de la Fraga, presents a method to efficiently build a mesh of triangles from a contour map of a terrain. The proposed approach includes intermediate points among contour lines to avoid the problem of flat triangles. The intermediate points are selected from the skeleton of the contour lines, and their heights are calculated automatically.

Barilla and Spann present in chapter 26 an experimental analysis of color-based texture image classification in order to evaluate whether or not the color and texture information should be used jointly or separately. Their results show that, indeed, color and texture information should be treated separately.

In chapter 27, López-García et al. report a software performance comparison of ten blind signature schemes that have been proposed between 1983 until 2008. The chapter provides a brief introduction to the basic concepts of blind digital signatures, and then provides an algorithmic description of the ten schemes studied along with the corresponding main arithmetic building blocks.

Finally, in chapter 28, Hernández León et al. propose a new algorithm for mining frequent itemsets. The proposed approach compresses the data while maintaining the necessary semantics for the frequent itemsets. This algorithm was found to be more efficient than other approaches that use traditional compression algorithms.

We we wish to thank all the authors for their high-quality contributions to this volume.

Finally, we wish to express our appreciation to LOGOS Verlag for their accomplished handling of the manuscript, for their understanding and for their patience.

Carlos A. Coello Coello Alexander Poznyak José Antonio Moreno Cadenas Vadim Azhmyakov Editors

CINVESTAV-IPN, Mexico City, Mexico, March 2010

Contents

Part I Automatic Control and Mechatronics						
1 Error estimates of mixed finite element methods for semilinear optimal control problems Zuliang Lu 3						
2 Sliding Mode Control Approach combined with Block Control for a Unified Power Flow Controller (UPFC) in a Small Power System Fidel Robles-Aguirre, Alexander Loukianov, Leonid Fridman, J.M. Cañedo 21						
3 Closed-Loop Identification for a Velocity Controlled DCServomechanism: Theory and Experiments Rubén Garrido, Roger Miranda41						
4 Practical stability of neutral and retarded type time delay systems: LMI's approach <i>R. Villafuerte and S. Mondié</i> 53						
5 Relationship Between Dynamic Programming and the MaximumPrinciple for Impulsive Hybrid LQ Optimal Control ProblemsR. Galvan-Guerra, V. Azhmyakov75						
6 Task Space Robot Control Using Joint Proportional Action Rubén Garrido, E. Alberto Canul, Alberto Soria						
7 Further Properties of Carleman Linearization <i>Irving Sánchez, Joaquín Collado</i>						
8 Finite Element Modelling and Unbalance Compensation for an Asymmetrical Rotor-Bearing System with Two Disks <i>M. Arias-Montiel, G. Silva-Navarro</i>						

9 Semiactive Control for the Unbalance Compensation in a Rotor-Bearing SystemA. Cabrera-Amado, G. Silva-Navarro143
10 Design of a Passive/Active Autoparametric Pendulum Absorber forDamped Duffing Systems G. Silva-Navarro, L. Macias-Cundapi, B. Vazquez-Gonzalez
Part II Solid-State Materials and Electron Devices
11 Characterization of Nanocrystalline ZnO Grown on SiliconSubstrates by DC Reactive Magnetron SputteringG. Juárez-Díaz, A. Esparza-García, M. Briseño-García, G. Romero-ParedesR., J. Martínez-Juárez, R. Peña-Sierra179
12 Thermodynamic Stability of $A^{III}B_x^V C_y^V D_{1-x-y}^V$ Semiconductor Alloys Salvador F. D. Albarrán, Alicia G. G. Noguez, Patricia R. Peralta, VyacheslavA. ElyukhinA. Elyukhin
13 Electrical, Relaxation and Crystallization Properties of Ge ₂ Sb ₂ Te ₅ Alloys <i>E. Morales-Sánchez, E. Prokhorov, G. Trapaga, M. A. Hernández-</i> <i>Landaverde, J. González-Hernández</i>
Part III Biomedical Engineering, Circuits and Communication Systems
14 Suitability of Alternative Methods of Time Delay Measurements for Ultrasonic Noninvasive Temperature Estimation in Oncology Hyperthermia Arturo Vera, Lorenzo Leija, Abraham Tellez, Ivonne Bazán, Antonio Ramos 223
15 Assessing the Statistical Nature of the MAI in a WSN based on IR-UWB for Cognitive-like Operation Fernando Ramírez-Mireles, Angel Almada
16 Hybrid Space-Time Codes for MIMO Wireless Communications Joaquin Cortez, Alberto Sanchez, Miguel Bazdresch, Omar Longoria, RamonParra267
17 Calculation of the Radiation Pattern of On-Board Antennas Placed over Complex Structures using Physical Optics Including the Contribution of the Shadowed Areas Lorena Lozano, Francisco Saez de Adana, Manuel Felipe Cátedra

18 Analisys of both a Voltage-to-Current Converter and a MemoryCell Implemented using the Multiple-Input Floating Gate MOSFETTransistorA. Medina-Vázquez, J. Moreno-Cadenas, F. Gómez-Castañeda, LuisMartín-Flores, M. E. Meda-Campaña
19 A CMOS Pipelined Multiplier Based on a New High-Speed Low-Power Full-Adder Cell <i>Mariano Aguirre-Hernandez, Monico Linares-Aranda</i>
20 A Reaction-Diffusion Model for the Production of Autowaves and its Application to Navigation Control of Mobile Robots <i>José Antonio Medina Hernández, Felipe Gómez Castañeda, José Antonio</i> <i>Moreno Cadenas</i>
Part IV Computer Science and Computer Engineering
21 Optimization of a Type-2 Fuzzy Controller for Output Regulation of a Servomechanism with Backlash via Genetic Algorithms Nohe R. Cazarez-Castro, Luis T. Aguilar, Oscar Castillo
23 Moodle UML model and its Security Vulnerabilities Juan Carlos Galán Hernández, Miguel Ángel León Chávez
24 Towards a Reconfigurable Platform to Implement Security Architectures of Wireless Communications Standards Based on the AES-CCM Algorithm Ignacio Algredo-Badillo, Claudia Feregrino-Uribe, René Cumplido, Miguel Morales-Sandoval
25 A Method to Generate Automatically a Triangulated Irregular Network from Contour Maps <i>Luis Gerardo de la Fraga</i>
26 Image classification with colour and texture using the Complex Wavelet Transform <i>Maria E. Barilla, Michael Spann</i>
27 A Software Performance Comparison of Blind Signature Schemes

Lourdes López-García, Luis Martínez-Ramos, Francisco Rodríguez-Henríquez 459

XVI Contents

Analisys of both a Voltage-to-Current Converter and a Memory Cell Implemented using the Multiple-Input Floating Gate MOSFET Transistor

A. Medina-Vázquez¹, J. Moreno-Cadenas¹, F. Gómez-Castañeda¹, Luis Martín-Flores¹, and M. E. Meda-Campaña²

¹ Department of Electrical Engineering, CINVESTAV-IPN, México City, Mexico

² CUCEA, Guadalajara University, Zapopan, Jalisco, México

Summary. Differences and advantages that the Multi-Input Floating Gate MOS (MIFGMOS) transistor has versus the conventional CMOS transistor are shown. In order to do this, the design and implementation of both a Voltage to Current Converter (VIC) cell and a Memory Current Cell (MIC) using MIFGMOS transistors is presented. The development is based in mathematical and simulation analysis as well as in experimental results. Both cells present good performance and linearity according to theoretical analysis and presents low voltage operation and low power consumption, despite the long channel technology. These characteristics are very important in analog and mixed signal applications, like mobile communications systems. The cells presented here can be part of a low-voltage sample and hold circuit but applications are not restricted. Additionally, some comparison between simulation and experimental results obtained when testing five 3-input MIFGMOS transistor are included in order to show the properties and behavior of this transistor.

18.1 Introduction: Multiple-Input Floating Gate MOSFET Transistor

The floating gate MOSFET (FGMOS) transistor is a simple MOSFET transistor with its gate completely insolated, that means, without metal contact to the outside. The gate is immersed in an oxide layer and the electric charge into the floating gate does not flow to either side. For this reason, the floating gate transistor was used in implementing EPROM or EEPROM memories some decades ago [1], because the electric charge remain in the floating gate for a long time. However, currently it is possible to implement a great variety of analog and digital circuits based in FGMOS transistors [2] and [3], respectively. These kinds of circuits can be applied in communications systems as shown in [4], neural network [5], biomedical systems, etc. In general, in all these applications, low supply voltage and low power consumption are desired.

Because the gate of the MOSFET in a FGMOS is floating, it is necessary implement some mechanism to manipulate the electric charge or voltage on the



Fig. 18.1. Basic MIFGMOS transistor structure: (a) schematic, (b) 3-input MIFGMOS layout, (c) electric symbol

floating gate. The most popular techniques are: using ultraviolet light [6], Fowler-Nordheim tunneling [7], hot electron injection [8], quasi-floating gate [9], and capacitive coupling [10]. The approach presented here is focused to using the capacitive coupling in order to control the voltage on the floating gate. It is necessary to note that using this technique, multiple inputs are possible.

As shown in Fig. 18.1(a), Multi-input Floating Gate MOS (MIFGMOS) transistor has many input gates $(V_1, V_2, ..., V_n)$ coupled to the gate of a conventional MOSFET trough capacitors $(C_1, C_2, ..., C_n)$. Fig. 18.1(b) shows the layout of a three-input MIFGMOS and part (c) shows the electrical symbol.

The coupling capacitors are formed by the poly1 layer (the floating gate) and poly2 layer. It is recommendable to use poly1-poly2 capacitors because the gate is always built with poly1 layer and furthermore, there is more capacitance per unit area than using metal1-metal2 capacitors. Hence, input voltages $(V_1, V_2, ..., V_n)$ are coupled through the capacitors to the floating gate to modify the drain-source current [10]. In this manner, the input voltages can be coupled and added arithmetically to the floating gate. This is because the floating gate voltage is a function of the input voltages V_i and the coupling capacitors C_i . In general, the input voltages V_i are called control inputs. Thus, the floating gate voltage can be approximated by [11]:

$$V_{FG} = \sum_{i=1}^{n} \frac{C_i}{C_T} V_i + \frac{C_{FGS}}{C_T} V_S + \frac{C_{FGD}}{C_T} V_D + \frac{Q_{FG}}{C_T}$$
(18.1)

where *n* is the number of inputs coupled capacitively, C_i are the coupling capacitances, V_i are the input voltages, V_S and V_D are the source and drain voltages, respectively, Q_{FG} is the initial charge in the floating gate, and C_T is given by:

$$C_T = \sum_{i=1}^{n} C_i + C_{FGD} + C_{FGS}$$
(18.2)

In (18.2), C_{FGD} and C_{FGS} are the floating-gate-drain and floating-gate-source parasitic capacitances, respectively.

In this way, the first approximation equation to determine the drain-source current in sub-threshold regime, triode and saturation region are, respectively:

$$I_{DS} = I_{DO} \frac{W}{L} \exp\left(\frac{V_{FGS} - V_{th}}{\eta V_{ther}}\right) \text{ if } V_{FGS} < V_{th} \text{ and } V_{DS} < 4V_{ther}$$
(18.3)

where V_{ther} is the thermal voltage approximated by $\frac{kT}{q}$ (k is the Bolztman constant, T is temperature and q the electron electric charge). I_{DO} is a drain-source current when $V_{FGS} = V_{th}$ and η is a constant, usually 1, and V_{th} is the MOSFET threshold voltage.

$$I_{DS} = K' \frac{W}{L} \left((V_{FGS} - V_{th}) - \frac{V_{DS}}{2} \right) V_{DS} \text{ if } 0 < V_{DS} < (V_{FGS} - V_{th})$$
(18.4)

where $K' = \mu_o C_{ox}$ and W/L is the MOSFET geometry

$$I_{DS} = K' \frac{W}{L} \left(V_{FGS} - V_{th} \right)^2 \text{ if } 0 < \left(V_{FGS} - V_{th} \right) < V_{DS}$$
(18.5)

In (18.3)-(18.5) V_{FGS} is approximated by (18.1).

On the other hand, an important consideration is the unpredictable charge stored in the floating gate when the MIFGMOS transistor is fabricated. This charge remain on the floating gate for a long time, so it can changes the circuit performance. To solve this problem, the technique presented in [12] is used here, where the undesirable electrical charge is removed during the manufacturing process using switchs formed by metal contacts.Other methods to discharge the initial charge in the floating gate (do not used here) are: ulraviolest light, Fowler-Nordheim technique and quasi-floating gate technique, all referenced above.

18.1.1 Simulation and d.c. results

To get the current-voltage simulation of the MIFGMOS transistor and compare it with the experimental results, some simulations models published in the literature were considered [13], [14], [15]. All this models have positive and negative characteristics and the search for better models continues. However, the model presented in [15] was considered in this work, because it calculates the floating gate voltage based in the parameters provided for the manufacturer and its SPICE implementation is simpler. Then, to compare the d.c. simulation results with the experimental results, five 3-input MIFGMOS coupled inputs were fabricated in 1.2 μ m technology. Table 18.1 shows the values of the coupling capacitances and ratio aspect as well other important parameters of each MIFGMOS transistors after they were fabricated. Additionally, Table 18.2 shows the capacitive parameters of the 1.2 μ m process.

Thus, the three inputs $V_{G1} = V_{G2} = V_{G2}$ of the MIFGMOS represented in Fig. 18.2 are connected toghether and they has been sweep while V_{DD} is kept constant. In Fig. 18.3, the experimental average results (measuring the experimental median results of five transistors) are ploted when $V_{DD} = 1.0V$ and $V_{DD} = 3.0V$, respectively. It is possible to see simulation results are according to experimental results.

Table 18.1. Coupling capacitances and ratio aspect of the 3-input MIFGMOS transistor

Parameter	Value	Description
C_1	50.1984fF	Coupling capacitor 1
C_2	40.9953	Coupling capacitor 2
C_3	96.6319	Coupling capacitor 3
W_n	6.0µm	Channel wide
L_n	3.6µm	Channel lenght
λ	$1.2 \mu m$	CMOS process technology
μ_o	$647.91 \ cm^2/Vs$	Low-field Mobility (n-type)
$K'(\mu_o C_{ox})$	$21.1 \mu A/V^2$	Transconductance parameter
V_{th}	0.59V	n-type MOSFET sub-threshold voltage
t_{ox}	316 Å	Gate-oxide thickness

Table 18.2. Capacitance parameters in the $1.2 \mu m$ CMOS process

Parameter	N+	P+	Poly1	Poly2	Metal1	Metal2	Units
Area(sustrate)	290	304	37	37	24	16	$aF/\mu m^2$
Area(N+ active)	-	-	1094	696	52	27	$aF/\mu m^2$
Area(P+ active)	-	-	1079	690	-	-	$aF/\mu m^2$
Area(Poly1)	-	-	-	581	46	23	$aF/\mu m^2$
Area(Poly2)	-	-	-	-	47	23	$aF/\mu m^2$
Area(metal1)	-	-	-	-	-	38	$aF/\mu m^2$
Fringe(sustrate)	73	157	-	-	30	26	aF∕µ m
Fringe(poly1)	-	-	-	-	60	43	aF/ μ m
Fringe(metal1)	-	-	-	-	-	55	aF/ μ m
Overlap(N+ active)	-	-	256	-	-	-	aF/ μ m
Overlap(P+ active)	256	-	-	-	-	-	aF/ μ m



Fig. 18.2. Configuration to analyze d.c. curves of the 3-input-MIFGMOS

18.1.2 Programmable threshold voltage

As it was mentioned early, the MIFGMOS transistor has a tuning property because it can increase or decrease its relative threshold voltage dynamically using a single



Fig. 18.3. Comparation between experimental and simulation I_{DS} vs. V_{G1} curves

coupled input gate. This can be interpreted as a programmable apparent threshold voltage. To show this, an experimental test is done setting the inputs of the transistor in Fig. 18.2 as follows: two inputs (V_{G2} and V_{G3}) are connected together to apply a sweep input voltage, and the input V_{G1} will be used to control the relative threshold voltage. The V_{G1} voltages take values of -5.0, -3.0, -1.0, 0.0, +1.0, +3.0 and +5.0 volts. In this case, the supply voltage V_{DD} is maintained constant with a value of 5.0V. Fig. 18.4 shows the I_{DS} vs. V_{G1} curves, where I_{DS} is the drain current of the transistor. We can note a particular case when V_{G1} =+5.0V, there is a small current flowing in the transistor even if the input voltage V_{G1} is zero. This could be a disadvantage in a circuit based on MIFGMOS transistor because is necessary to cut this current when the transistor is not required, using additional transistors as switches.

However, modifying the relative MIFGMOS threshold voltage, we can get positive consequence since the supply voltage and operation voltage can be reduced, e.g. in cascode configurations in a CMOS design, where to maintain the transistor working in the saturation region it is needed that each transistor satisfy V_{DS} =



Fig. 18.4. Drain-source current of MIFGMOS transistor when the apparent threshold voltage is varied (experimental results).

 $V_{GS} - V_{th}$, thus, if the threshold voltage V_{th} or the gate-source voltage V_{GS} can be manipulated, V_{DS} can be reduced, [16] and [17] and, consequently, we can reduce the supply voltage V_{DD} . Moreover, decreasing the supply voltage, the total power dissipation of the circuit is decreased.

18.1.3 Other properties of the MIFGMOS

The MIFGMOS transistor has another propierty, that is, the possibility of a feedback loop to improve the linearity in a particular desing and this will be shown later. More even, using MIFGMOS transistors the circuit complexity is reduced, signal processing is simplified and the quiscient point in a circuit can be shifted [13]. All advantages mentioned above are very important both in analog and in mixed signal circuits design, particularly in applications which require low supply voltage and low power dissipation, as used in [18] and [19].

However, the MIFGMOS has some disadvantages when is compared with the conventional MOSFET. The most important disadvantages are: lower effective transconductance, lower output resistance, and lower frequency response. If we define the effective MIFGMOS transconductance (in saturation region) respect to a single input V_i as

$$g_{mi} = \frac{\delta I_{DS}}{\delta V_i} \tag{18.6}$$

from (18.5) and (18.6) we get the expression:

$$g_{mi} = \frac{\delta I_{DS}}{\delta V_i} = \frac{\delta}{\delta V_i} \left(\frac{1}{2} \mu_o C_{ox} \frac{W}{L} \left(\frac{C_i}{C_T} V_i + \sum_{x=2}^n \frac{C_x}{C_T} V_x - V_{th} \right) \right)$$
(18.7)

and

$$g_{mi} = \frac{C_i}{C_T} g_m \tag{18.8}$$

where g_m is the transconductance of the conventional MOSFET transistor. Note than the transconductance of the MIFGMOS respect to a single input is lower than the conventional MOSFET ($\frac{C_i}{C_T} < 1$).

18.2 Voltage to current converter based on MIFGMOS

The Voltage-to-current converter (VIC) cell based on the MIFGMOS transistor is presented and analyzed here to show the properties of the MIFGMOS such as: lowpower operation, good linearity at low voltage operation and configurable threshold voltage. The advantages mentioned above are very important both in analog and in mixed signal circuits design, particularly in applications which require low voltage operation and low power dissipation.

The main function of the VIC is to convert an input voltage to an output current. We are interested in a VIC designed with MIFGMOS transistors to take advantages about its properties mentioned above.

This cell consists of a linear transconductor and a p-type current mirror as a load, both implemented with MIFGMOS transistors, as shown in Fig. 18.5. In this cell M1 is the transconductor with M6 as a triode load. The p-type current mirror (M8-M11) operates as a load in order to reduce the channel-length modulation and improve the circuit gain. M1 transistor has a feedback loop between its drain and the floating gate through C_f capacitance to improve the linearity of the cell. However, if the cell has a V_{DDFG} voltage applied, it will be a voltage V_f coupled to the floating gate through C_f , thus, we have a current IM6, even if V_{in} is null. This could be an undesired effect. To cut this undesired current when the cell is not needed, we use the transistors M3, M5 and M7 as switches.

In the next subsection each part is analyzed and it is showed how the VIC cell proposed here requires less supply voltage maintaining good linearity than conventional MOSFET version.

18.2.1 Transconductor stage

Now, it is showed how the transconductor stage in the VIC in Fig. 18.5, proposed here, has better linearity than conventional MOSFET version.

Analyzing M1 transistor and based in (18.1), the floating gate voltage is calculated by:

$$V_{FG1} \approx \frac{C_{in}V_{in}}{C_T} \tag{18.9}$$

ignoring C_{GD} , C_{GS} , C_{GB} and C_{ox} effects in order to facilitate hand calculations without losing generality.



Fig. 18.5. Voltage to current converter implemented with MIFGMOS transistors. M1 MIFGMOS is compared with a conventional MOSFET

Taking M6 triode load, M7 switch, and p-type current mirror together shown in Fig. 18.5 as a load called R_D , the drain voltage V_f of M1 in saturation region is:

$$V_f = V_{DDFG} - R_D \frac{\mu_o C_{ox}}{2} \frac{W_1}{L_1} \left(\frac{C_{in}}{C_T} V_{in} + \frac{C_f}{C_T} V_f - V_{th} \right)^2$$
(18.10)

where μ_o is the mobility of charge carriers, C_{ox} is the MOSFET gate oxide capacitance by unit area, V_{th} is the threshold voltage for n-type MOSFET, and L and W are the large and width of the MOSFET transistor, respectively.

Developing the squared term in (10), we get:

$$V_{f} = V_{DDFG} - R_{D} \frac{\mu_{o} C_{ox}}{2} \frac{W_{1}}{L_{1}} (V_{th}^{2} - \frac{2C_{in}}{C_{T}} V_{in} V_{th} - \frac{2C_{f}}{C_{T}} V_{f} V_{th}$$
(18.11)
+ $\frac{2C_{in} C_{f}}{C_{T}^{2}} V_{f} V_{in} + \frac{C_{in}^{2}}{C_{T}^{2}} V_{in}^{2} + \frac{C_{f}^{2}}{C_{T}^{2}} V_{f}^{2})$



Fig. 18.6. Iout vs. Vin in MIFGMOS transconductor (simulation)

In (18.11) there are three squared terms. In this case, V_{th} is constant (≈ 0.7 V, according to the 1.2 μm technology), but we can have control in the two last terms: $\frac{C_{in}^2}{C_T^2}V_{in}^2$ and $\frac{C_f^2}{C_T^2}V_f^2$.

So, linearity improves increasing C_T since $(C_T = C_{in} + C_f)$, it means, it is necessary to increase C_{in} or C_f . We opted arbitrary to increase the value of C_f to increase C_T . It should be noted this property is not possible using conventional MOSFET transistor.

Fig. 18.6 shows the IM6 current (drain of M6 transistor), when the input voltage of the VIC (V_{in}) is swept, also, C_f is varied. Note the good linearity with 2.0V voltage supply (V_{DDFG}) using a resistor as a load ($R_D = 10k\Omega$). Also, note that the output current IM6 is different to zero when $V_{in} = 0V$. This is because the feedback voltage V_f is present when V_{DDFG} is applied. This current means static power consumption but it can be cut using the switches mentioned above. Here, $C_{in} = 100 fF$.

Fig. 18.7 shows a simulated comparison between the drain current flowing through M1 transistor working as the transconductor shown in Fig. 18.5, both MOSFET and MIFGMOS version. In these cases, the supply voltage is 3.0V. We can see better linearity in MIFGMOS version but better dynamic range (RD) in MOSFET case.

18.2.2 Low-supply voltage p-type current mirror

Now, it is showed how the p-type current mirror proposed and implemented with MIFGMOS transistors (Fig. 18.8(a)) will require less supply voltage than conventional MOSFET version (Fig. 18.8(b)). So, we demonstrate that:

$$V_{DDC} > V_{DDFG} \tag{18.12}$$

Each version is analyzed and compared.



Fig. 18.7. Comparison between MIFGMOS and conventional MOSFET transconductor (simulation)



Fig. 18.8. (a) P-type current mirror implemented with MIFGMOS transistor and (b) implemented with MOSFET transistors only

a. Current mirror implemented using conventional MOSFET transistors only

Analyzing the circuit showed in Fig. 18.8(b), the supply voltage V_{DDC} is:

$$V_{DDC} = V_{GS2} + V_{GS1} + V_{load}$$
(18.13)

where V_{load} is the voltage provided for the current source I_{ref} . In this case, we consider all the transistors working in the saturation region, hence the source to gate voltage of M1 or M2 is:

$$V_{SG1} = \sqrt{\frac{2I_{ref}}{\mu_o C_{ox}} \cdot \frac{L_1}{W_1}} + V_{thp}$$
(18.14)

where V_{thp} is the threshold voltage for p-type MOSFET transistor.

Now, combining (13) and (14) we obtain:

$$V_{DDC} = 2V_{thp} + \sqrt{\frac{2I_{ref}}{\mu_o C_{ox}}} \left(\sqrt{\frac{L_2}{W_2}} + \sqrt{\frac{L_1}{W_1}}\right) + V_{load}$$
(18.15)

The result obtained in (18.15) is very important because it shows the way the supply voltage depends of V_{load} and both the aspect ratio and V_{thp} . Also, we will use (18.15) to demonstrate (18.12).

b. Current mirror implemented using the conventional MOSFET transistor

Similar analysis is realized for the current mirror MIFGMOS version. In Fig. 8(a), the current through M2 transistor in saturation region is:

$$I_{ref} = \frac{\mu_o C_{ox}}{2} \frac{W_2}{L_2} \left(V_{DDFG} - V_{FG2} - V_{thp} \right)^2$$
(18.16)

where the floating gate voltage of M2 (V_{FG2}) is given by:

$$V_{FG2} = \frac{C_1 V_1 + C_b V_b}{C_T}$$
(18.17)

In (18.17), V_b is a small bias voltage applied to the p-type MIFGMOS transistors in order to decrease the relative threshold voltage of M2 and consequently to reduce the supply voltage (V_{DDFG}). C_1 and C_b are coupling capacitors. Later, ignoring the parasitic capacitances C_{GD} , C_{GS} , and C_{GB} and combining (18.16) and (18.17), the supply voltage is:

$$V_{DDFG} = \sqrt{\frac{2I_{ref}}{\mu_o C_{ox}} \frac{L_2}{W_2}} + \frac{C_b}{C_T} V_b + \frac{C_1}{C_T} V_1 + V_{thp}$$
(18.18)

where the voltage in node V_1 is given by:

$$V_1 = V_{SG1} + V_{load} (18.19)$$

Finally, combining (18.14), (18.18), (18.19):

$$V_{DDFG} = V_{thp} + \frac{C_1}{C_T} V_{thp} + \frac{C_b}{C_T} V_{load} + \sqrt{\frac{2I_{ref}}{\mu_o C_{ox}}} \left(\sqrt{\frac{L_2}{W_2}} + \frac{C_1}{C_T} \sqrt{\frac{L_1}{W_1}}\right)$$
(18.20)



Fig. 18.9. *I*_{out} vs. *V*_{DDFG} for different geometries (simulation)

Equation (18.20) calculates the minimum supply voltage needed for the current mirror transistors working in the saturation region. Fig. 18.9 shows the curves of V_{DDFG} voltage versus I_{out} . In this case, a current of $5\mu A$ is applied as a target and $C_1 = C_b = 100 fF$.

It is possible to watch that modifying the ratio aspect of the transistor the supply voltages V_{DDFG} ca be reduced. This is shown in the simulation results in Fig. 18.9 for different values of W, maintaining $L = 3.6 \mu m$. When W is increased, less supply voltage V_{DDFG} is required to copy the target current maintaining the transistors in saturation region (see points *a* and *b*). However, a tradeoff exists between low supply voltage and linearity and this must be taken into account in the design process.

In order to analyze the effect of the bias voltage V_b in the current mirror in Fig. 18.8(a), Fig. 18.10 shows the current mirror operation varying V_b . We can see that applying a very small or negative voltage on V_b , the supply voltage V_{DDFG} is reduced maintaining the transistor in the saturation region (see points *c* and *d*). In this case, $I_{ref} = 5\mu A$ and $C_1 = C_b = 100 fF$.

Now, it is demonstrated than (18.12) is true. First, note that V_{DDC} in (18.15) and V_{DDFG} in (18.20) are always positive. Then subtracting (18.20) and (18.15), we have:

$$V_{DDC} - V_{DDFG} = V_{load} \left(1 - \frac{C_1}{C_T} \right) + V_T \left(1 - \frac{C_1}{C_T} \right)$$

$$+ \sqrt{\frac{2I_{ref}}{\mu_o C_{ox}} \frac{L_1}{W_1}} \left(1 - \frac{C_1}{C_T} \right) + \frac{C_b}{C_T} V_b$$
(18.21)

Since $0 < C_1 < C_T$:

$$0 < (1 - \frac{C_1}{C_T}) < 1 \tag{18.22}$$



Fig. 18.10. V_b impact in the p-type curent mirror. I_{out} vs. V_{DDFG} changing V_b (simulation)

Hence, all terms in (18.21) are always positives (V_b could be zero), so we conclude that $V_{DDC} > V_{DDFG}$.

18.3 VIC implementation

The VIC cell was fabricated in a $1.2\mu m$ CMOS technology, double poly, double metal. Fig. 18.11 shows the experimental results when we measured the linearity of the VIC. To do this, an input voltage is swept in V_{in} input and the output current I_{out} is measured. Note the good linearity of this cell with a voltage supply of 1.7V.

Fig. 18.12 (scope image) shows the operation of the VIC cell when is used as a code detector in a signal processing. In this case, V_{in} is a binary sequence "10011100", with amplitude of 0V to 500mV at 500kHz and a supply voltage V_{DDFG} of 1.7V. For reason of easy, the output voltage was measure using a 1.0k Ω resistive load between the drain of M9 transistor and ground, which it has a maximum value of 8.0mV. Now, the maximum output current of the VIC will be $8mV/1.0K\Omega = 8\mu A$. Meanwhile, if this cell operates with a higher supply voltage of 3.0V, a speed operation of 2.0MHz is possible; but, it must take into account the load (discrete resistor of 1.0k Ω) in the drain of M9 used in the experimental measures because it will be a limiting factor. As we can see, this cell has a limited speed operation, thus, it is necessary to consider this characteristic in the design process.

18.4 Memory current cell (MIC)

In this section, a current memory cell implemented using MIFGMOS transistor is introduced. This cell is formed by n-type transistors current mirror. In previous



Fig. 18.11. linearity of the MIFGMOS VIC (experimental results)



Fig. 18.12. Operation of the VIC at 1.7 V supply voltage (experimental result).

section the low-voltage operation of the current mirror implemented with MIFGMOS transistor was shown. Thus, the memory current cell shown in Fig. 18.13 stores an analog current as a charge and, connecting both the VIC and MIC cells in a cascade array, a low-voltage sample and hold circuit in current mode can be implemented.

The MIC implemented with MOSFET transistor is shown in Fig. 18.13(a) and the MIFGMOS version proposed here is shown in Fig. 18.13(b). The MIFGMOS MIC is a current mirror (M2, M4 and M5) used as a memory, where M1, M3 and M6 operate as switches.

This cell operates as follows: when M1 and M3 switches are closed and the M6 switch is opened, I_{in} generates a voltage in the gate of M4. Later, cutting M1



Fig. 18.13. Memory Current Cell (a) conventional MOS, (b) MIFGMOS version

and M3, a charge is stored in the gate-source parasitic capacitance (C_L) inherent to the MIFGMOS transistor M4. This stored charge will be proportional to the I_{in} amplitude, representing the memory. When the M6 is closed, the voltage stored in C_L will generate a current through M4, M5 and M6. In this case, the bias voltages V_{bias1} and V_{bias2} decrease the relative threshold voltage to get a minimal supply voltage in cascode configuration.

The MIC implemented with MIFGMOS transistors will have a better linearity with a minimal supply voltage V_{DDx} because transistors M4-M6 are working in saturation region with less voltage thanks to the applied bias voltages to the floating gate. Thus, we take advantages from the properties of the MIFGMOS transistor to build a low-voltage MIC with a good linearity.

18.4.1 MIC implementation

The MIC shown in Fig. 18.12(b) using MIFGMOS transistors was implemented in a1.2 μ m CMOS technology, double poly, double metal. In order to see the linearity of this cell, Fig. 18.15 shows a swept input current I_{in} versus the output current through the transistors M4-M6 of the MIC. Here, the current is reduced intentionally with a rate of 3:1. The output current was measured between the drain of M6 and V_{DDX} voltage.

Finally, Fig. 18.17 shows the operation of the MIC with a supply voltage V_{DDx} of 1.7V (scope image). In this case, a low frequency sinusoidal signal of 500Hz is sampled using a 500 kHz sampling pulsed signal (0-3V). For reason of easy, the output is read in voltage mode using a R_D load of $220K\Omega$ to get an observable signal. Again, the speed of the cell is limited for high frequency applications because the high value of the resistor and the RC constant involved in all the measuring process. In order to enhance the bandwidth of the cell, a more elaborate I/V converter



Fig. 18.14. Linearity of the MIFGMOS MIC. Iin vs. Iout. (experimental results)



Fig. 18.15. Operation of the MIC with a voltage supply of 1.7V (experimental result).

is recommended. However, both cells are recommended for current mode circuit design.

18.5 Conclusions

This document shows than MIFGMOS transistor is an important alternative to implement analog circuits with low voltage operation and good linearity based in the advantages of this transistor. To demonstrate this, the analysis and implementation of two cells using MIFGMOS transistors were presented: a voltage to current converter cell and a memory current cell. Two important properties of MIFGMOS transistors



Fig. 18.16. MIcrofotography of the VIC

were shown: variable threshold voltage and feedback possibility. Combining these properties, a voltage to current converter with good linearity at low supply voltage was implemented. We compare the performance of the VIC in a MOSFET version versus a MIFGMOS version and we demonstrated with analytical and experimental results than MIFGMOS has a better linearity applying a low supply voltage, but with a low frequency operation. This must be taken into account in the process design.

On the other hand, a MIC using the MIFGMOS transistor was implemented in order to obtain good linearity with low supply voltage. We got satisfactory results despite the long-channel technology.

Both cells were implemented in a $1.2\mu m$ CMOS technology, double poly, double metal. The VIC operates satisfactory with 1.7V supply voltage at 0.5MHz with a power consumption of $20\mu W$. Also, the MIC can operate with a supply voltage of 1.7V with $12\mu W$ power consumption at 0.5MHz.

Finally, these cells can be used to implement a sample and hold circuit operating in current mode, but theirs applications are not limited. Fig. 18.16 and 18.17 show the micropotography of the VICand the MIC, respectively.

Acknowledgment

We appreciate the support of CONACyT, Mexico

References

- Asquith, J., Chang-Ling S., Hung Bun C. "A two-dimensional numerical model of a floating-gate EEPROM transistor", Int. J. Electronics, Vol. 85, No. 6, pp. 697 - 712 (1998)
- [2] Topor-Kamiski, L., and Holajn, P. "Multiple-input floating-gate MOS transistor in analogue electronics circuit". Bulletin of the Polish Academy of Sciences, Vol. 52, No. 3. pp. 251 - 256. (2004)



Fig. 18.17. MIcrofotography of the MIC

- [3] Kotani, K., Shibata, T., Imai, M., and Ohmi, T. "Clock-controlled neuron-MOS logic gates" IEEE Transactions on Circuits and Systems II: Analog and Digital Signal Processing, Vol. 45, No. 4, pp. 518 - 522. (1998)
- [4] Yamasaki, T., Nakayarna, T., and Shibata, T. "A Low-Power Switched-Current CDMA Matched Filter With On-Chip V-I and I-V Converters". Symposium on VLSI Circuits Digest of Technical Papers. pp. 214 - 217.(2004)
- [5] Suresh, V., Katharine, R., and Baiju, M. "Adaptive Neuron Activation Function with FGMOS Based Operational Transconductance Amplifier", IEEE Computer Society Annual Symposium on VLSI, pp. 353 - 356.(2008)
- [6] Yngvar Berg, ivind Nss, Mats E. Hvin and Henning Gundersen. "Ultra Low-Voltage Floating-Gate (FGUVMOS) Amplifiers" Analog Integrated Circuits and Signal Processing. Springer Netherlands. Volume 26, No. 1 (2001)
- [7] Lenzlinger, M. and Snow, E. H., "Fowler-Nordheim tunneling in thermally grown SiO2," Journal of Applied Physics, vol. 40, p. 278 (1969)
- [8] Hasler, P. "Continuous-Time Feedback in Floating-Gate MOS Circuits", IEEE Transactions on Circuits and Systems-II: Analog and Digital Signal Processing, Vol. 48, No. 1, pp. 56 - 64. (2001)
- [9] Ramrez-Angulo, J., Urquidi, C., Gonzlez-Carvajal, R., Torralba, A., and Lpez-Martn, A. "A new family of low-voltage analog circuits based on quasi-floating-gate transistors". IEEE Transactions on Circuits and Systems II: Analog and Digital Signal Processing, Vol. 50, No. 5, pp. 214 - 220. (2003)
- [10] Shibata, T. and Ohmi, T. "A Functional MOS Transistor Featuring Gate-Level Weighted Sum and Threshold Operations". IEEE Transactions on Electron Devices, Vol. 39, Issue 6, pp. 1444-1455. (1992)
- [11] Antonio J. Lopez Martin, Alfonso Carlosena, Jaime Ramrez Angulo. "D/A Conversion Based on Multiple-Input Floating-Gate MOST" 42nd Midwest Symposium on Circuits and Systems. Volume: 1, On page(s): 149-152 vol. 1. (1999)
- [12] Rodriguez-Villegas, E. "Solution to trapped Charge in FGMOS Transistors", Electronics Letters, Volume 39, Issue 19, pp. 1416 - 1417. (2003)
- [13] Rodriguez-Villegas, E. "Low Power and Low-Voltage Circuit Design with the FGMOS Transistor", London, United Kingdom. The Institution of Engineering and Technology. pp. 6 - 7, and 22 - 28. (2006)
- [14] Ochiai, T. and Hatano, H. "A Proposition on Floating Gate Neuron MOS Macromodeling for Device Fabrications". IEICE Trans. Fundamentals, Vol. E82-A, No. 11, pp. 2485 -2491. (1999)

- [15] Guan, H. and Tang, Y. "Accurate and efficient models for the simulation of neuron MOS integrated circuits". Int J. Electronics, Vol. 87, No. 5, pp. 557-568. (2000)
- [16] Rajput, S., and Jamuar, S. "Low-Voltage Analog Circuit Design Techniques". Circuits and Systems Magazine, IEEE. Vol. 2, Issue: 1, pp. 24-42.(2002)
- [17] Drakaki, M., Fikos, G., and Siskos, S. (2005), "Analog Signal Processing Circuits Using Floating Gate MOS Transistor", 5th International Conference on Technology and Automation ICTA'05. http://icta05.teithe.gr/papers/59.pdf. (2005)
- [18] Liou, M. and Chiueh, T. "A low-power digital matched filter for direct-sequence spreadspectrum signal acquisition". IEEE J. Solid-State Circuits, vol. 36, no. 6, pp. 933-943. (2001)
- [19] Yamasaki, T., Nakayama, Y., and Shibata, T. "A Low-Power and Compact CDMA Matched Filter Based on Switched-Current Technology". IEEE Journal of Solid-State Circuits, Vol. 40, No. 4, pp. 926 - 932. (2005)